Material Composition for F11-200XXX42R

Product Information	
Part Number:	F11-200XXX42R
Part Description:	0.5mm Pitch Conn.
Part Weight (g):	(0.0122 * XXX) + 0.696

Process Data	
Peak Reflow (Deg. C)	260°C for 10 seconds
Termination Finish	Gold flash over Nickel
RoHS Compliant? (Y/N)	Yes

Note: Tin plating is subject to 1,000ppm max Lead impurity.

Homogeneous Material Location	Weight (g)	Tolerance	Substance Name	CAS #
Signal Contact - Copper Alloy	0.00428 * XXX	5%	Copper	7440-50-8
	0.000147 * XXX	1%	Nickel	7440-02-0
	0.000078 * XXX	0.5%	Magnesium	7439-95-4
	0.000032 * XXX	0.5%	Silicon	7440-21-3
Signal Contact - Plating	0.0001 * XXX	10%	Nickel	7440-02-0
	0.0001 * XXX	10%	Gold	7440-57-5
Power Contacts - Copper Alloy	0.0675	5%	Copper	7440-50-8
	0.00232	1%	Nickel	7440-02-0
	0.00123	0.5%	Magnesium	7439-95-4
	0.000508	0.5%	Silicon	7440-21-3
Power Contacts - Plating	0.0018	10%	Nickel	7440-02-0
	0.0018	10%	Gold	7440-57-5
Solder Clips - Brass	0.036	5%	Copper	7440-50-8
	0.0185	1%	Zinc	7440-66-6
Solder Clips - Plating	0.0017	10%	Nickel	7440-02-0
	0.0017	10%	Tin	7440-31-5
Moulding (total weight)	(0.00745 * XXX) + 0.563	6%	33% GF LCP	
Containing:	(0.00484 * XXX) + 0.366	6%	Liquid Crystal Polymer	147310-94-9
	(0.00247 * XXX) + 0.186	6%	Glass Fibre	65997-17-3
	(0.000067 * XXX) + 0.00507	6%	Carbon Black	1333-86-4
	(0.000075 * XXX) + 0.00563	6%	Other	-

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